半導體、構裝及被動元件應用 **Advanced Ceramics Technology Forum:**

Semiconductor, Advanced Packaging and Passive Components Applications



Prof. Jun Akedo , AIST

New Possibilities for Room Temperature Ceramic Coatings Applied in the High-Power Semiconductor and Passive Component Industry



Prof. Jun Mizuno, NCKU

Initiatives for Advanced Heterogeneous integration



Prof. Clive Randall, PSU

Rethinking Design, Reliability and Processing of Passive Components

- Four masters will deliver special lectures, inviting relevant renowned researchers to give keynote speeches.
- 4 Sessions: Semiconductor, Package, Passive Component, and Other.
- Multiple exhibitions related to advanced ceramics.
- Simultaneous exhibition of contemporary ceramic artworks on-site.
- Each session can accommodate a maximum of 120 people.

時間

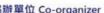
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國立台北科技大學

億光大樓 集思會議山川







先進陶瓷技術論壇:半導體、構裝及被動元件應用 Advanced Ceramics Technology Forum:

Semiconductor, Advanced Packaging and Passive Components Applications

Forum Agenda Planning

5/26			
8:00 – 9:00	Registration		
9:00 – 9:30	Opening		
	Take a Picture		
Semiconductor Session			
9:30 – 10:15	Plenary Speaker I	Prof. Akedo Jun, AIST	
	New Possibilities for Room Temperature Ceramic Coatings Applied in the High- Power Semiconductor and Passive Component Industry		
10:15 – 10:30	Break Time		
10:30 – 11:00	Keynote Speaker S1	Manager: Dr. Lee., Yong-Jay, ITRI	
		ALD material synthesis	
11:00 – 11:30	Keynote Speaker S2	Prof. Tseng, Tseung-Yuen, NCTU	
11.00 – 11.30		Ferroelectric Ceramic Applied in FeRAM	
11:30 – 12:00	Keynote Speaker S3	Deputy Division Director. Hsiao, Ta-Ching, ITRI	
		Component Semiconductor	
12:00 – 13:00	Lunch		
Advanced Package Session			
13:00 – 13:45	Plenary Speaker II	Prof. Jun Mizuno, NCKU	
	Initiatives for Advanced Heterogeneous integration		
13:45 – 14:30	Plenary Speaker III	Dr. Yoshiki Takahashi, AGC	
	Glass Core or Interposer		
14:30 – 15:00	Break Time		
15:00 – 15:30	Keynote Speaker P2	Prof. Lin, Re-Ching, FCU	
		Development, Market Trends, and Challenges of RF Front- End Technology	
15:30 – 16:00	Keynote Speaker P3	Prof. Hsu. Ying-Chao, NTUT	
		about COWOS	

主辦單位Organizers



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Advanced Ceramics Technology Forum:

Semiconductor, Advanced Packaging and Passive Components Applications

Forum Agenda Planning

5/27			
8:00 – 9:00	Registration		
Passive Component Session			
9:00 – 9:45	Plenary Speaker III	Prof. Clive Randall	
	Rethinking Design, Reliability and Processing of Passive Components		
9:45 – 10:15	Keynote Speaker C1	Prof. Rer. Nat. Jörg Töpfer	
		Functional Ceramics for Magnetic, Thermoelectric and Thermistor Applications	
10:15 – 10:30	Break Time		
10:30 – 11:00	Keynote Speaker C2	Prof. Hung. I-Ming, YZU	
		Li Ceramic Batteries:	
11:00 – 11:30	Keynote Speaker C3	Deputy Division Director. Dr. Lu, Chun-An, ITRI	
		Embedded Capacitor	
11:30 – 12:00	Keynote Speaker C4	Prof. Tu. Chi-Shun, FJU	
		Superb Capacitive Energy Storage in Bismuth Ferrite Based Multilayer Ceramics	
12:00 – 13:30	Lunch		
Advanced Material · Equipment & Measurement Session			
13:30 – 14:00	Keynote Speaker M1	Manager: Chen. Chiung-Hsiung	
		Ceramic High-Frequency Dielectric Measurement	
14:00 – 14:30	Keynote Speaker M2	Prof. Tseng. Wenjea J., NCHU	
		Semiconducting Ceramic Nanohybrids for Enhanced Gas- Sensing Applications	
14:30 – 15:00	Keynote Speaker M3	Prof. Shih. Yueh-Ting, NTUT	
		Accelerating the Development of Glass Materials through Computational Methods	
15:00 – 15:30	Break Time		
15:30 – 17:00	Technical Symposium Clive Randall, Sea-Fue Wang, Akedo Jun, Jun Mizuno, Yoshiki Takahashi		

主辦單位Organizers









